

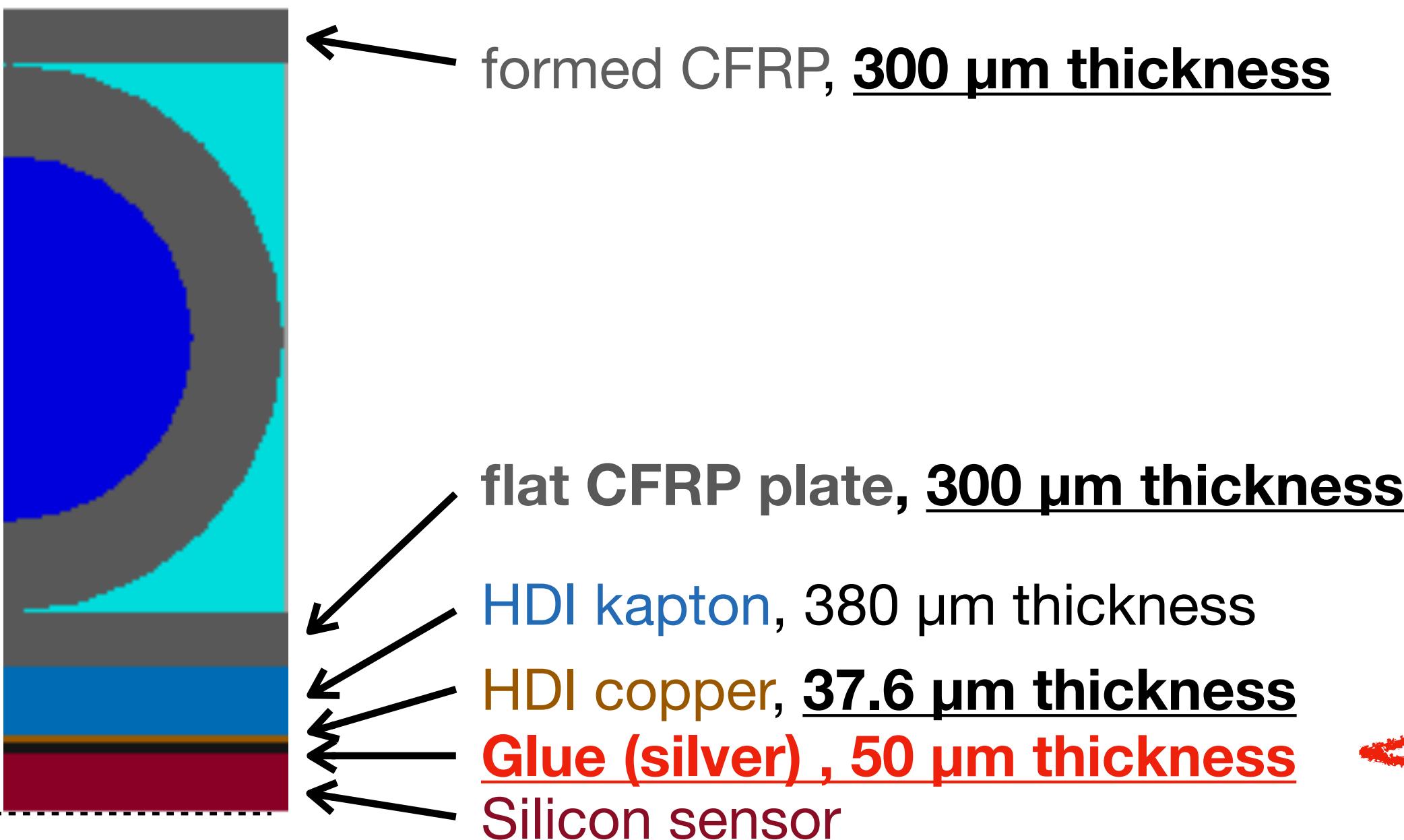
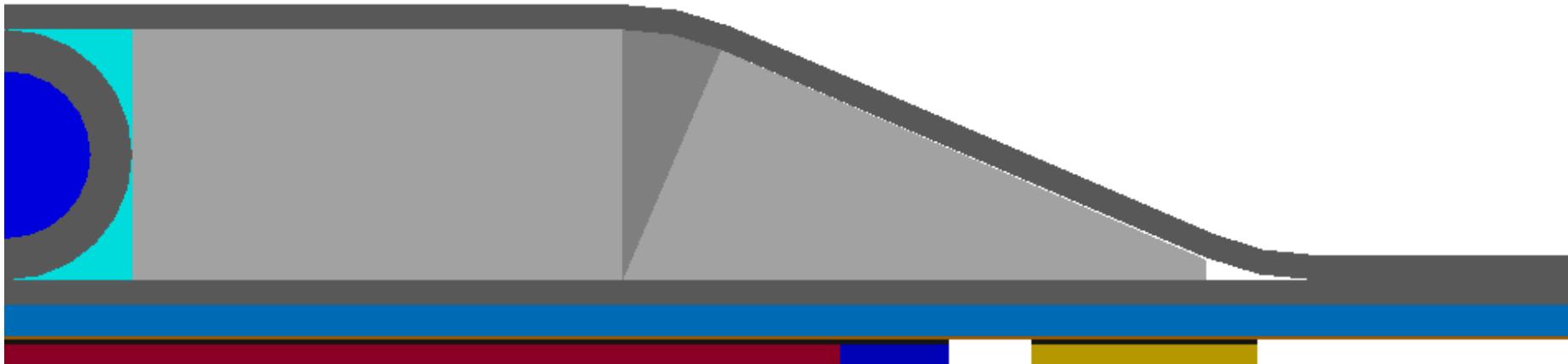
INTT Weekly Meeting, 22/July/2020

# **Updates on the Glue Thickness for Geant4 Model**

Genki Nukazuka (RBRC)

# Thickness of the Silicon Sensors

## Updated model

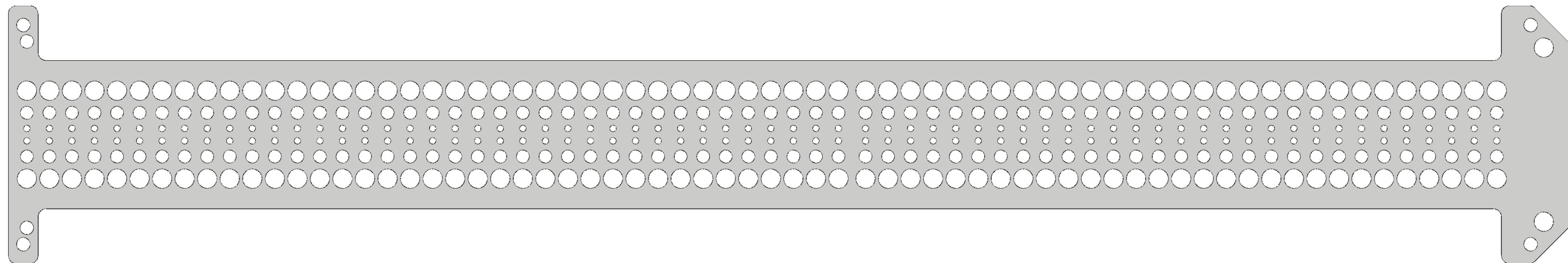


Realistic value  
should be input!

# Thickness of the Silicon Sensors

## INTT Sensor Glue Mask

for a  
half ladder

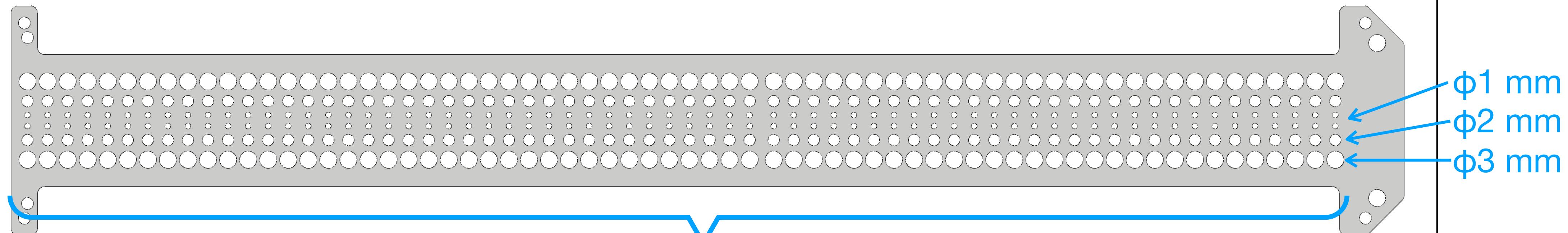


- The mask is 50um thick.
- The holes are 3mm, 2mm and 1 mm is diameter from the edge to the center of a sensor.
- The gap between 3mm holes is 0.5mm.
- May negatively impact cooling. Need to check (FEA).

# Thickness of the Silicon Sensors

## INTT Sensor Glue Mask

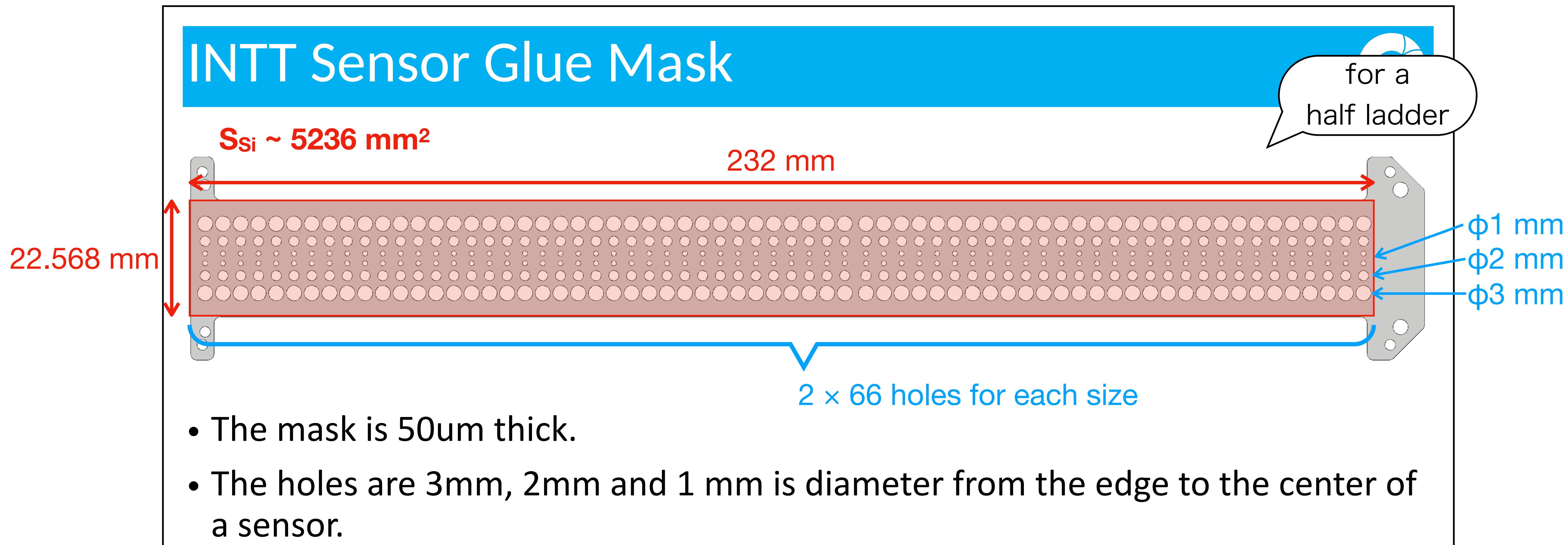
for a  
half ladder



- The mask is 50um thick.
- The holes are 3mm, 2mm and 1 mm is diameter from the edge to the center of a sensor.

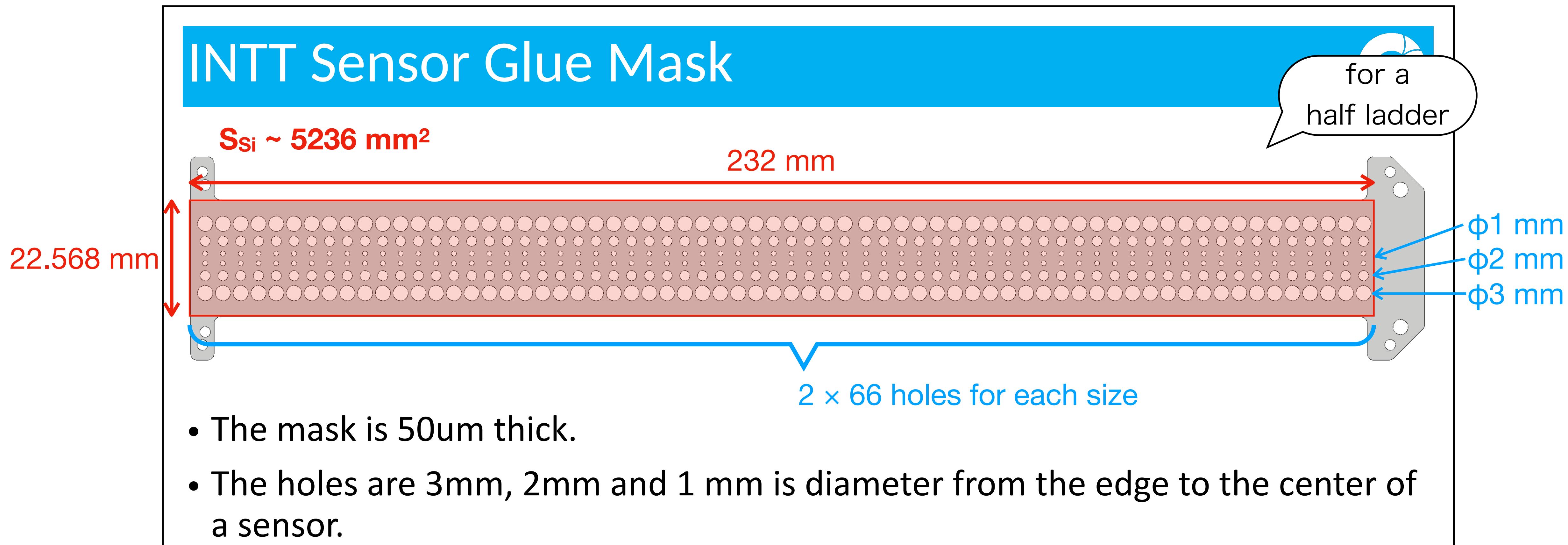
$$\begin{aligned} S_{\text{holes}} &= 2 \times 66 \times (S_{\phi 1} + S_{\phi 2} + S_{\phi 3}) \\ &= 2 \times 66 \times (0.25 + 1 + 2.25) \times \pi \text{ mm}^2 \\ &\sim 1451 \text{ mm}^2 \end{aligned}$$

# Thickness of the Silicon Sensors



$$\begin{aligned}S_{holes} &= 2 \times 66 \times (S_{\phi 1} + S_{\phi 2} + S_{\phi 3}) \\&= 2 \times 66 \times (0.25 + 1 + 2.25) \times \pi \text{ mm}^2 \\&\sim 1451 \text{ mm}^2\end{aligned}$$

# Thickness of the Silicon Sensors



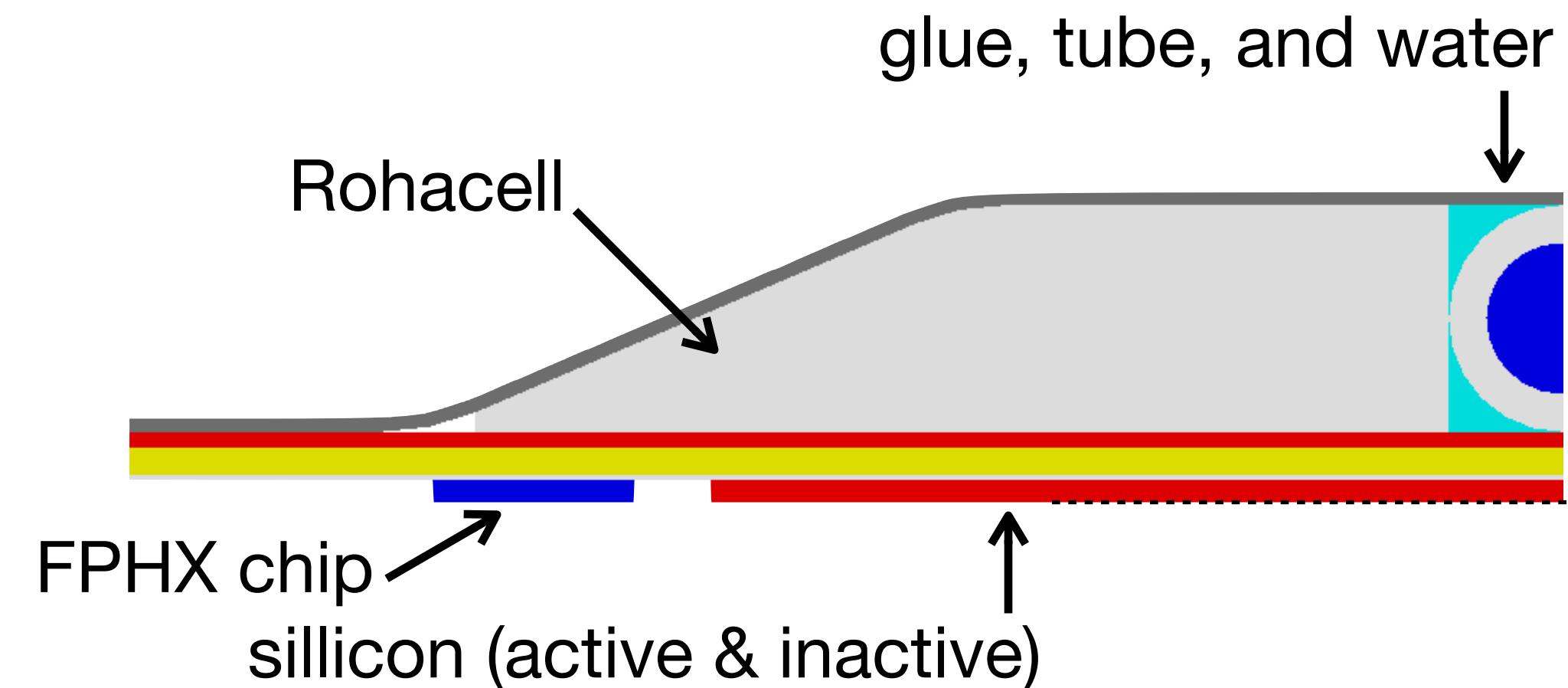
$$\begin{aligned} S_{\text{holes}} &= 2 \times 66 \times (S_{\phi 1} + S_{\phi 2} + S_{\phi 3}) \\ &= 2 \times 66 \times (0.25 + 1 + 2.25) \times \pi \text{ mm}^2 \\ &\sim 1451 \text{ mm}^2 \end{aligned}$$

$$\begin{aligned} \text{Effective thickness } t_{\text{eff}} &= t \times (S_{\text{holes}} / S_{\text{Si}}) \\ &= 50 \mu\text{m} \times 0.277 \\ &\sim 14 \mu\text{m} \end{aligned}$$

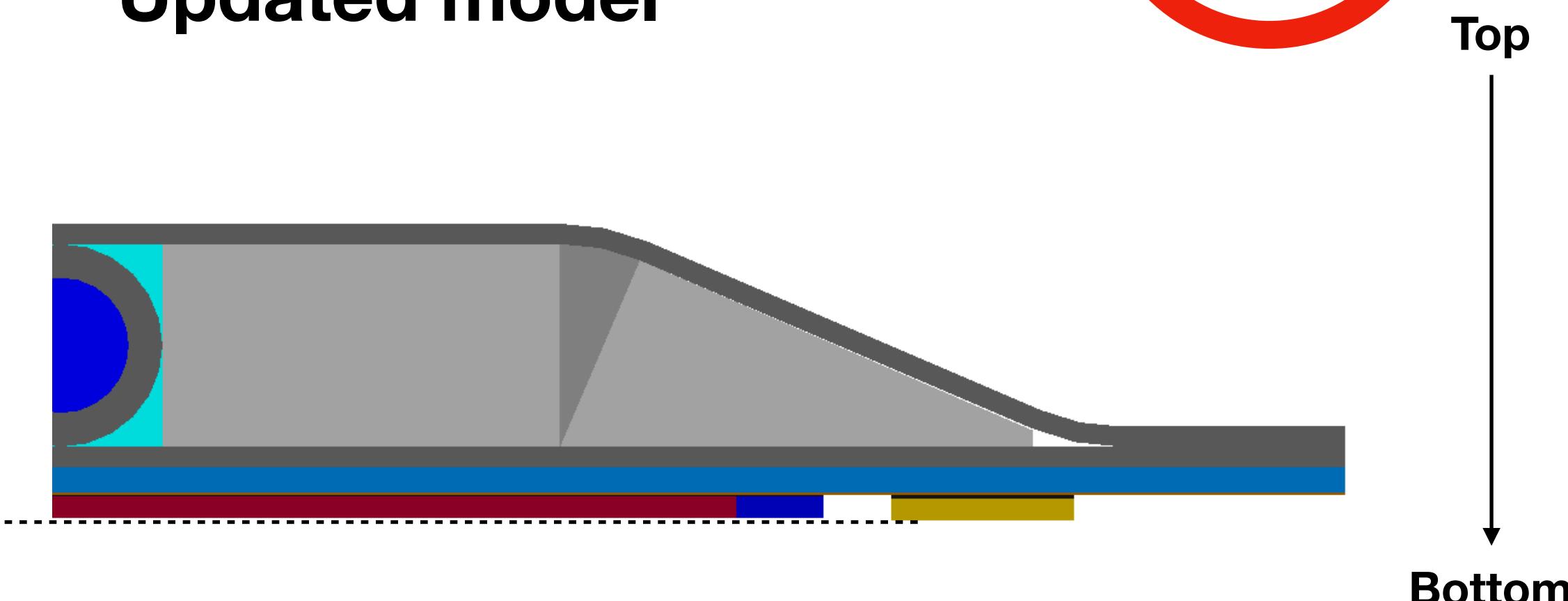
# Summary of Geometry of the ladder

Ver  
22.Jul  
2020

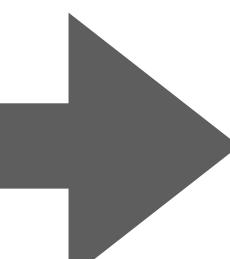
## Model in the current repository



## Updated model



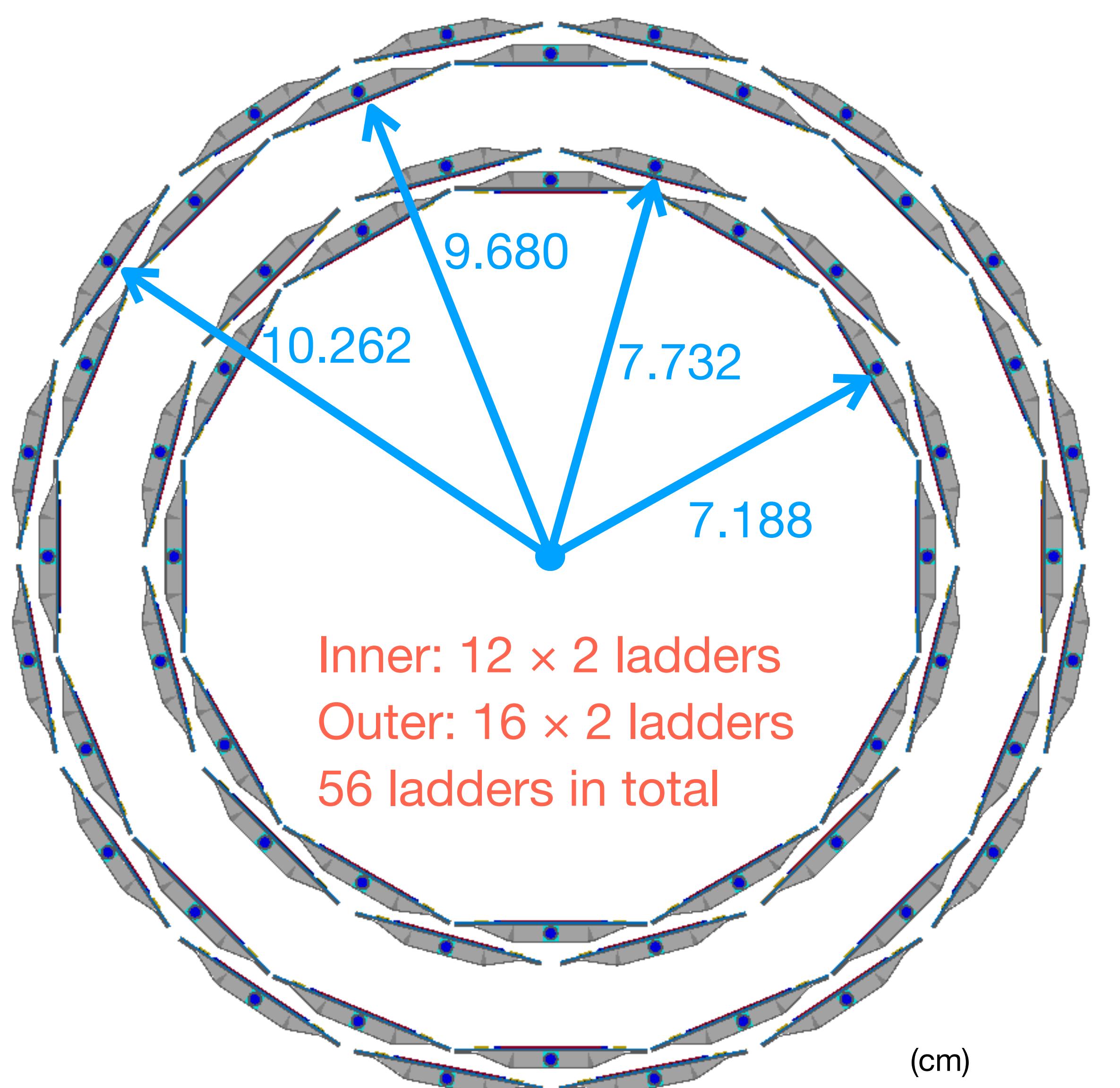
Top	Name	Material	X <sub>0</sub> (mm)	Thickness (μm)	X/X <sub>0</sub>
	formed CFRP	CFRP	256.41	190.5	0.07%
	Rohacel, CFRP tube, water				0.13%
	PGS	CFRP	256.41	200	0.08%
	Kapton of HDI	Kapton	285.70	380	0.13%
	Copper of HDI	Copper	14.36	52	0.36%
Bottom	Silicon/FPHX chips	Silicon	93.70	320	0.34%
					1.12%



Top	Name	Material	X <sub>0</sub> (mm)	Thickness (μm)	X/X <sub>0</sub>
	formed CFRP	CFRP	256.41	300	0.12%
	Rohacel, CFRP tube, water				0.13%
	<b>flat CFRP</b>	CFRP	256.41	300	0.12%
	Kapton of HDI	Kapton	285.70	380	0.13%
	Copper of HDI	Copper	14.36	37.6	0.26%
	<b>Silver epoxy glue</b>	Ag, epoxy	36.70	14	0.04%
Bottom	Silicon/FPHX chips	Silicon	93.70	320	0.34%
					1.14%

it was  
0.14%

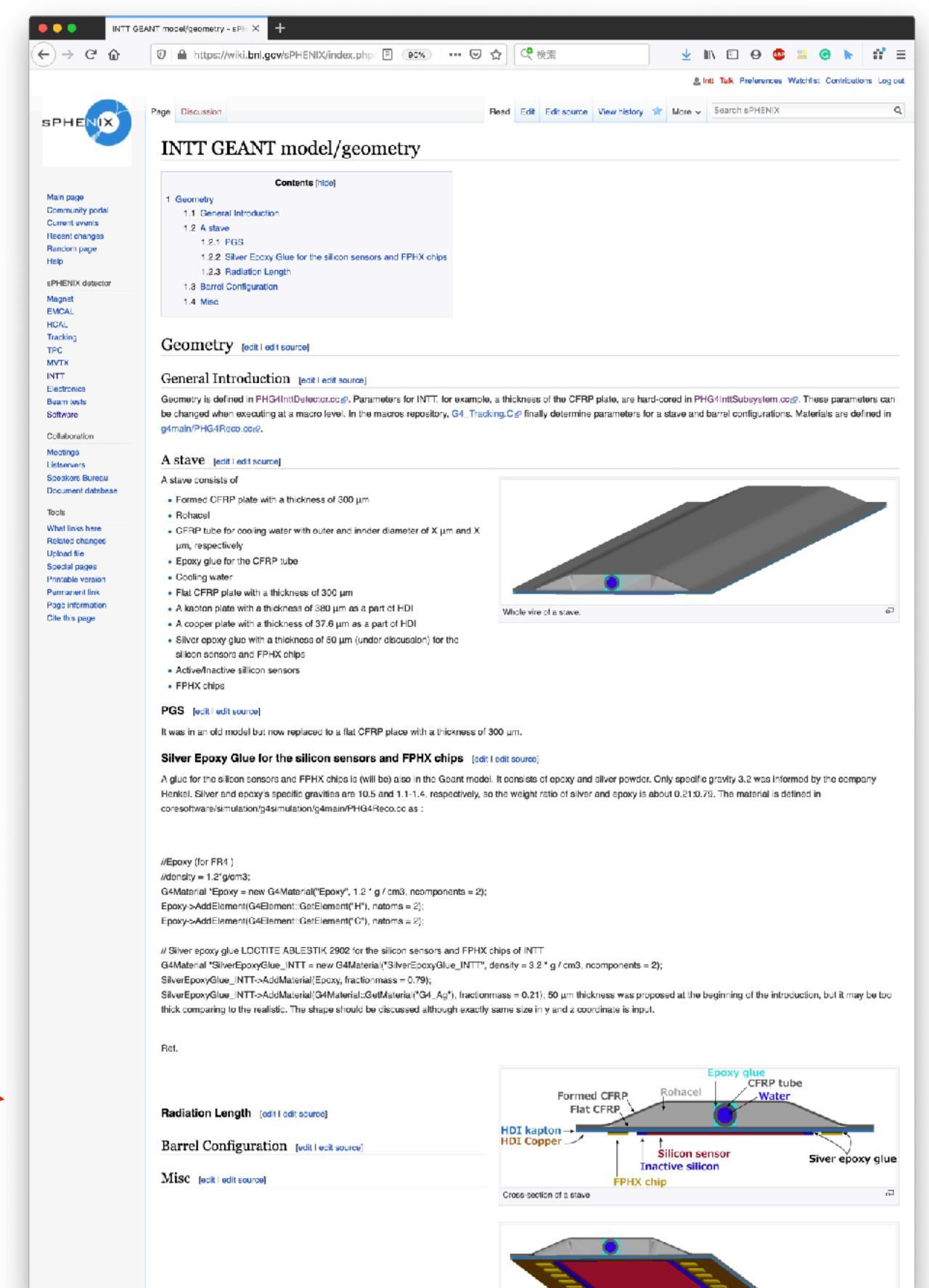
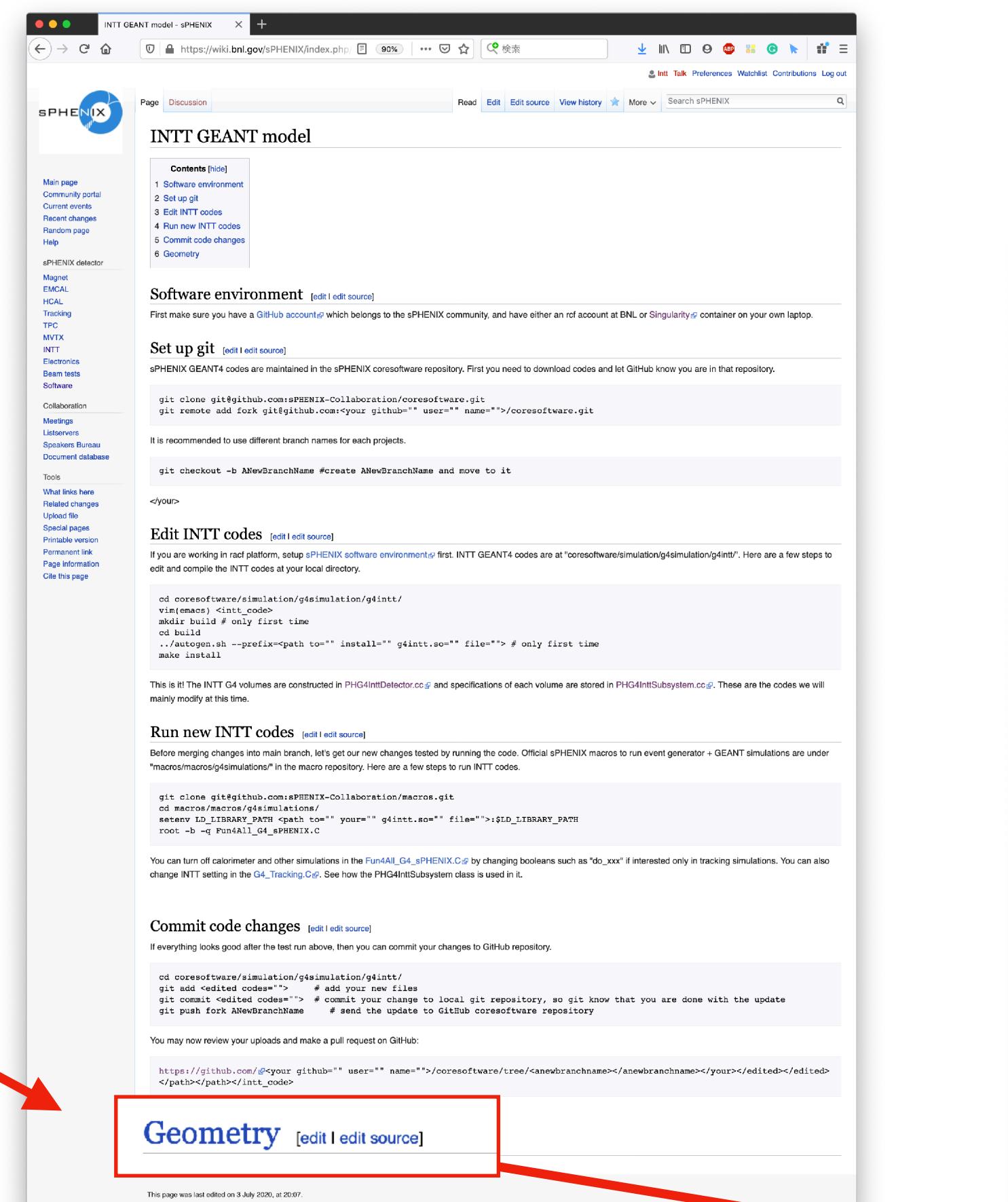
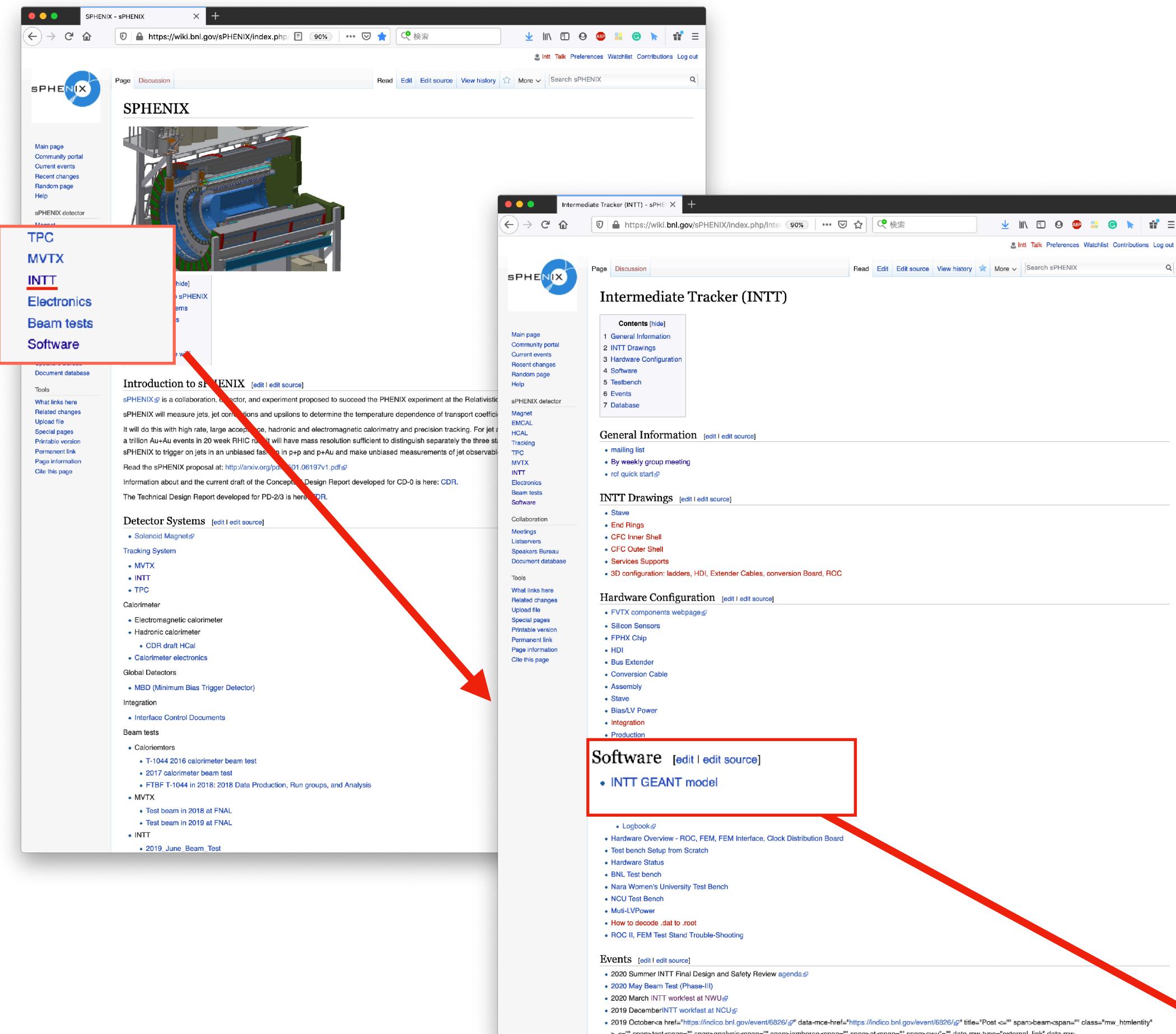
# Distance of layers from the beam-axis



36  $\mu\text{m}$  difference from  
the beam-axis to  
the chips and the sensors

The sensors should be  
placed as planned, right?

# Information: Wiki



under construction...